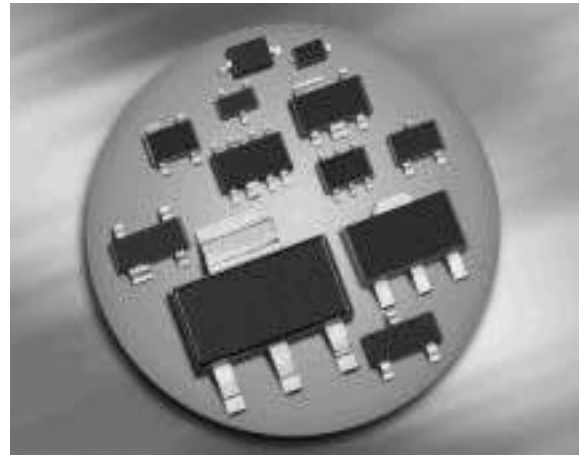
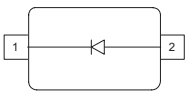
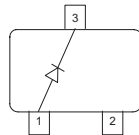
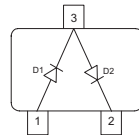
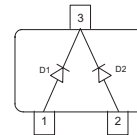
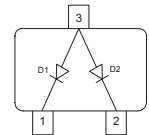
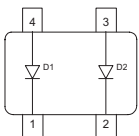


Silicon Schottky Diode

- General-purpose diode for high-speed switching
- Circuit protection
- Voltage clamping
- High-level detecting and mixing
- Pb-free (RoHS compliant) package ¹⁾
- Qualified according AEC Q101


BAS140W
BAS40-02L

BAS40

BAS40-04

BAS40-05
BAS40-05W

BAS40-06
BAS40-06W

BAS40-07
BAS40-07W

ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Package	Configuration	L_S (nH)	Marking
BAS140W	SOD323	single	1.8	white 4
BAS40	SOT23	single	1.8	43s
BAS40-02L	TSLP-2-1	single, leadless	0.4	FF
BAS40-04	SOT23	series	1.8	44s
BAS40-05	SOT23	common cathode	1.8	45s
BAS40-05W	SOT323	common cathode	1.4	45s
BAS40-06	SOT23	common anode	1.8	46s
BAS40-06W	SOT323	common anode	1.4	46s
BAS40-07	SOT143	parallel pair	2	47s
BAS40-07W	SOT343	parallel pair	1.6	47s

¹Pb-containing package may be available upon special request

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	40	V
Forward current	I_F	120	mA
Non-repetitive peak surge forward current $t \leq 10\text{ms}$	I_{FSM}	200	
Total power dissipation BAS140W, $T_S \leq 113^\circ\text{C}$ BAS40, BAS40-07, $T_S \leq 81^\circ\text{C}$ BAS40-02L, $T_S \leq 127^\circ\text{C}$ BAS40-04, BAS40-06, $T_S \leq 56^\circ\text{C}$ BAS40-06W, $T_S \leq 106^\circ\text{C}$ BAS40-05, $T_S \leq 31^\circ\text{C}$ BAS40-05W, $T_S \leq 98^\circ\text{C}$ BAS40-07W, $T_S \leq 118^\circ\text{C}$	P_{tot}	250 250 250 250 250 250 250 250	mW
Junction temperature	T_j	150	°C
Operating temperature range	T_{op}	-55 ... 125	
Storage temperature	T_{stg}	-55 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾ BAS140W BAS40, BAS40-07 BAS40-02L BAS40-04, BAS40-06 BAS40-06W BAS40-05 BAS40-05W BAS40-07W	R_{thJS}	≤ 150 ≤ 275 ≤ 90 ≤ 375 ≤ 175 ≤ 475 ≤ 205 ≤ 125	K/W

¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Breakdown voltage $I_{(BR)} = 10 \mu\text{A}$	$V_{(BR)}$	40	-	-	V
Reverse current $V_R = 30 \text{ V}$	I_R	-	-	1	μA
Forward voltage $I_F = 1 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 40 \text{ mA}$	V_F	250 350 600	310 450 720	380 500 1000	mV
Forward voltage matching ¹⁾ $I_F = 10 \text{ mA}$	ΔV_F	-	-	20	

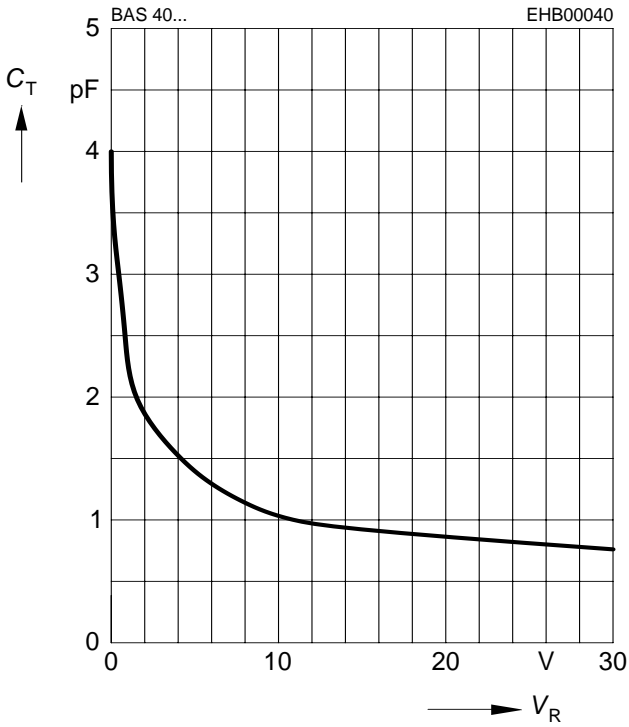
AC Characteristics

Diode capacitance $V_R = 0, f = 1 \text{ MHz}$	C_T	-	3	5	pF
Differential forward resistance $I_F = 10 \text{ mA}, f = 10 \text{ kHz}$	R_F	-	10	-	Ω
Charge carrier life time $I_F = 25 \text{ mA}$	τ_{rr}	-	-	100	ps

¹⁾ ΔV_F is the difference between lowest and highest V_F in a multiple diode component.

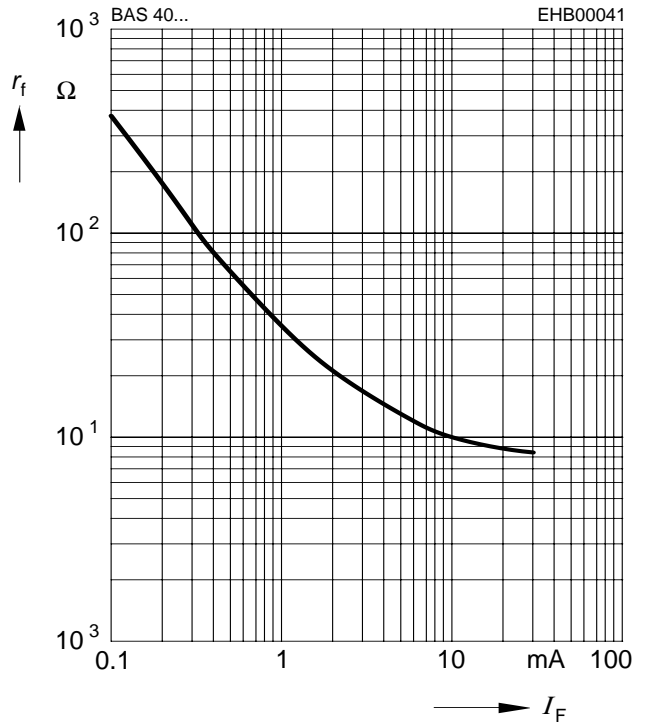
Diode capacitance $C_T = f(V_R)$

$f = 1\text{MHz}$



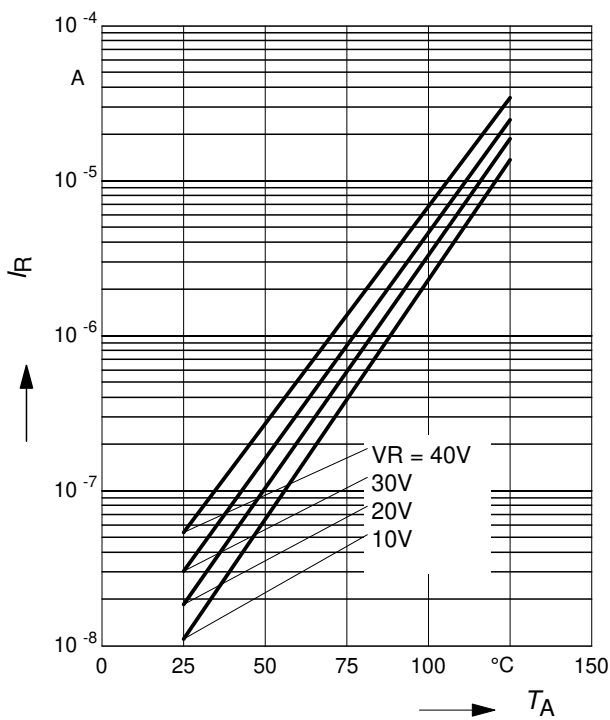
Forward resistance $r_f = f(I_F)$

$f = 10\text{kHz}$



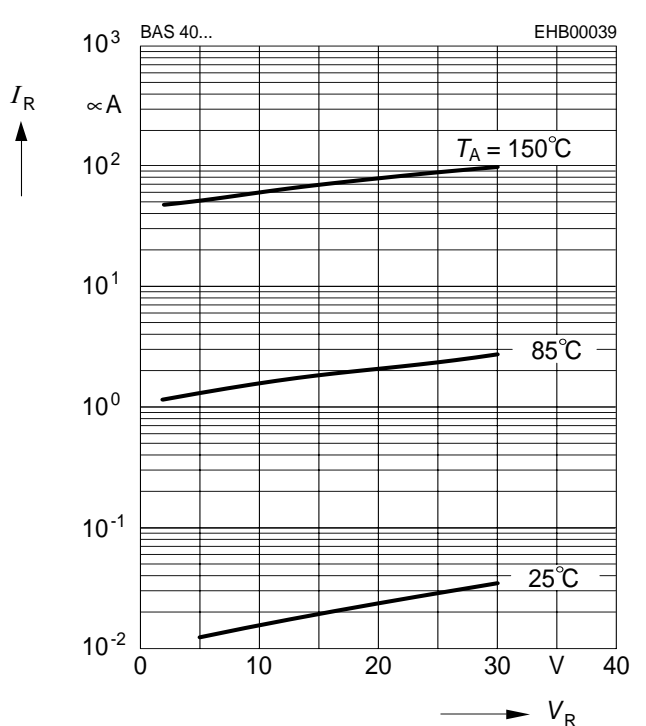
Reverse current $I_R = f(T_A)$

$V_R = \text{Parameter}$



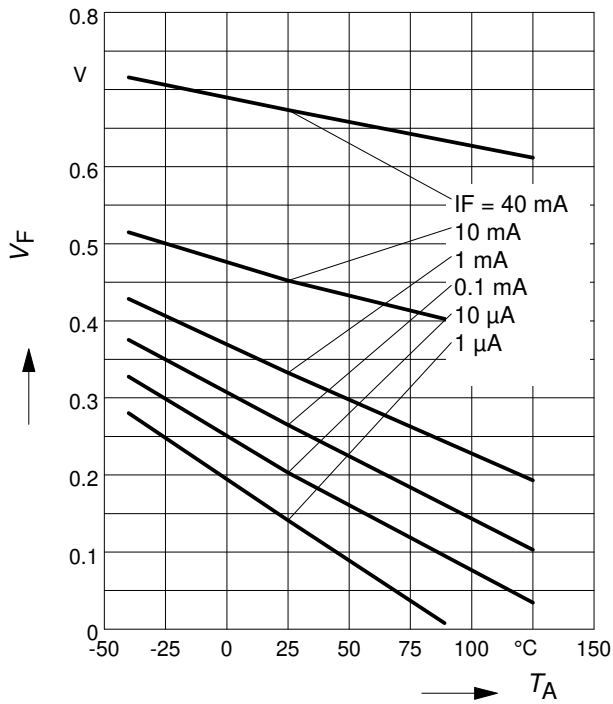
Reverse current $I_R = f(V_R)$

$T_A = \text{Parameter}$



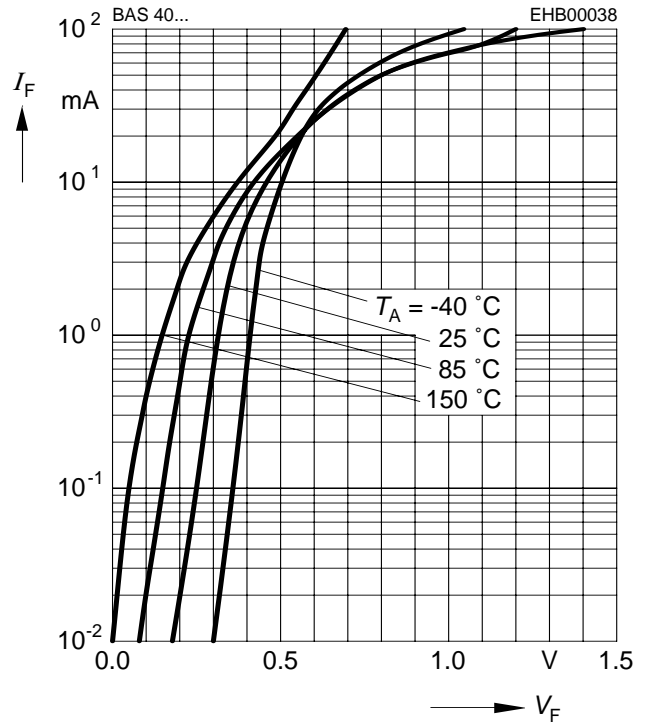
Forward Voltage $V_F = f(T_A)$

I_F = Parameter



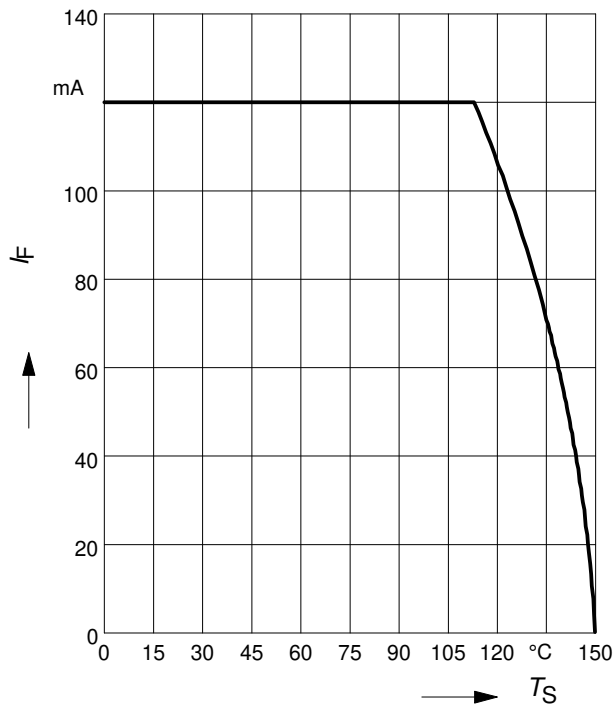
Forward current $I_F = f(V_F)$

T_A = Parameter



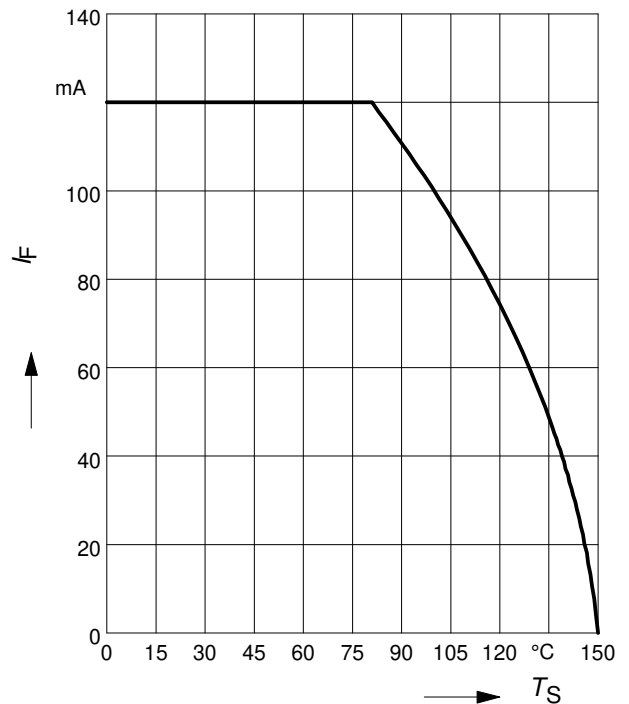
Forward current $I_F = f(T_S)$

BAS140W



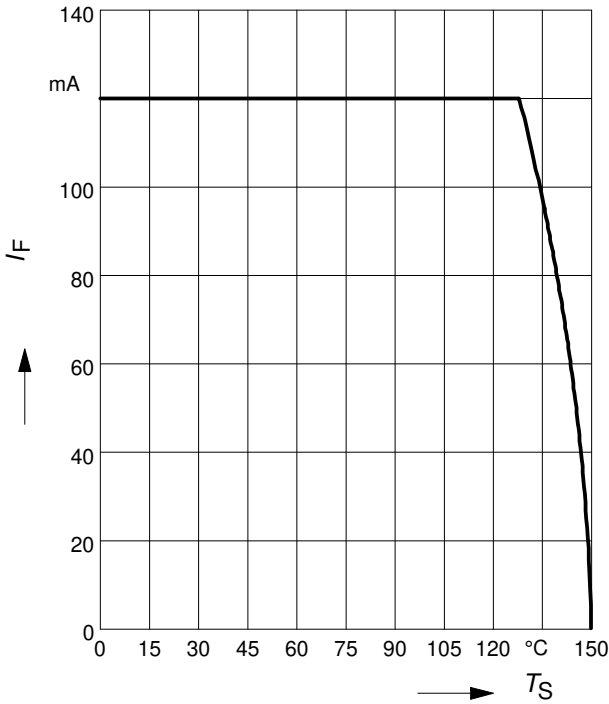
Forward current $I_F = f(T_S)$

BAS40, BAS40-07



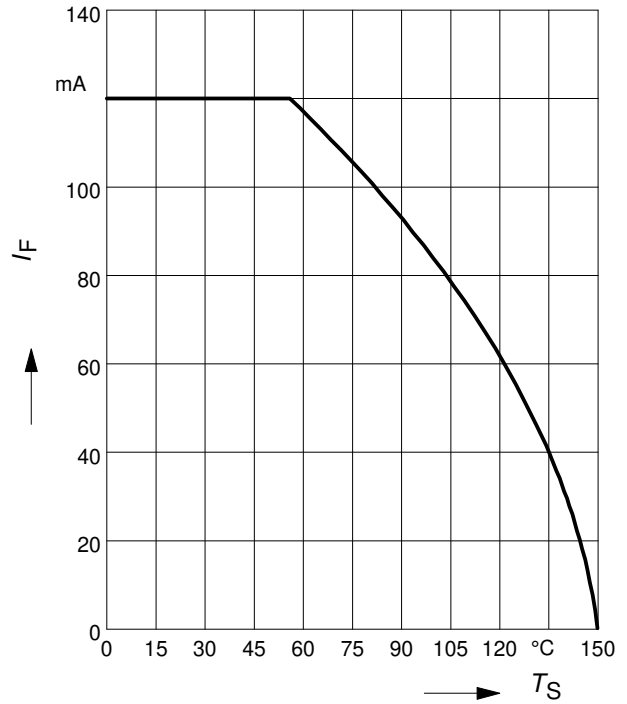
Forward current $I_F = f(T_S)$

BAS40-02L



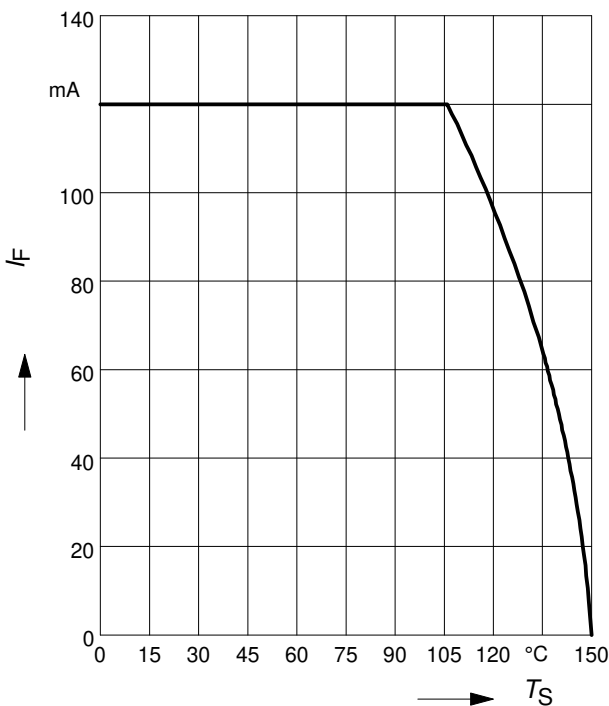
Forward current $I_F = f(T_S)$

BAS40-04, BAS40-06



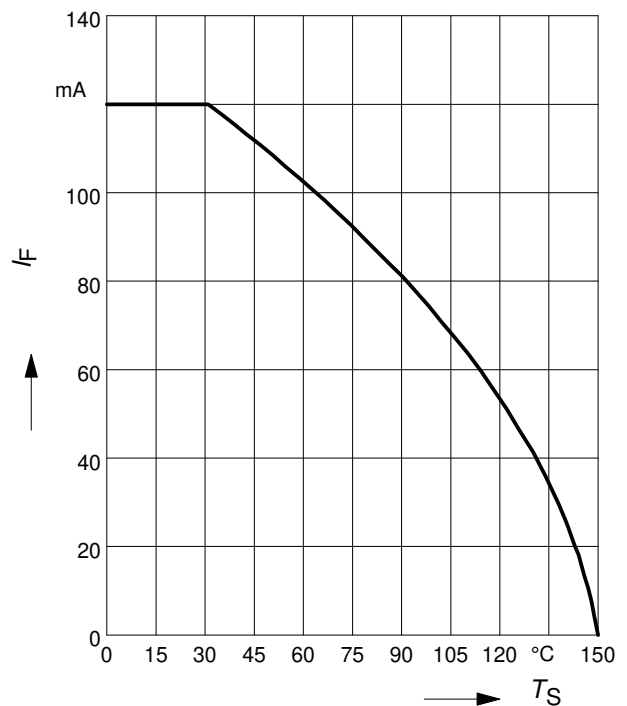
Forward current $I_F = f(T_S)$

BAS40-06W



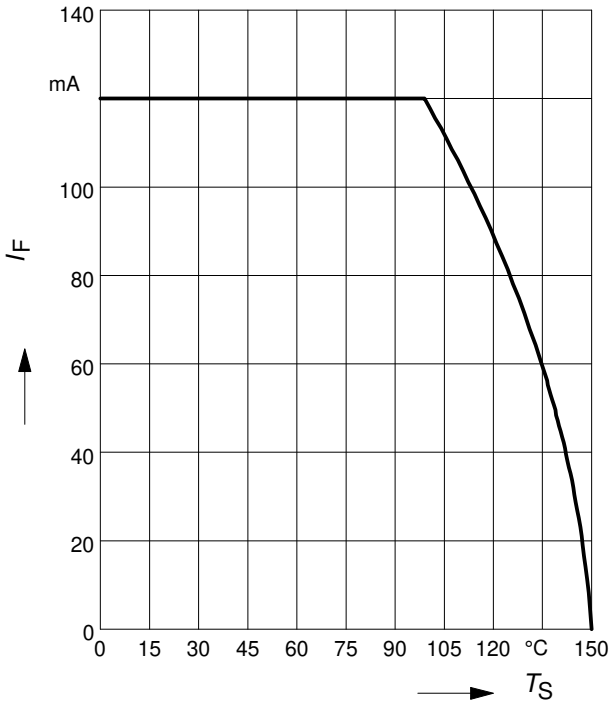
Forward current $I_F = f(T_S)$

BAS40-05



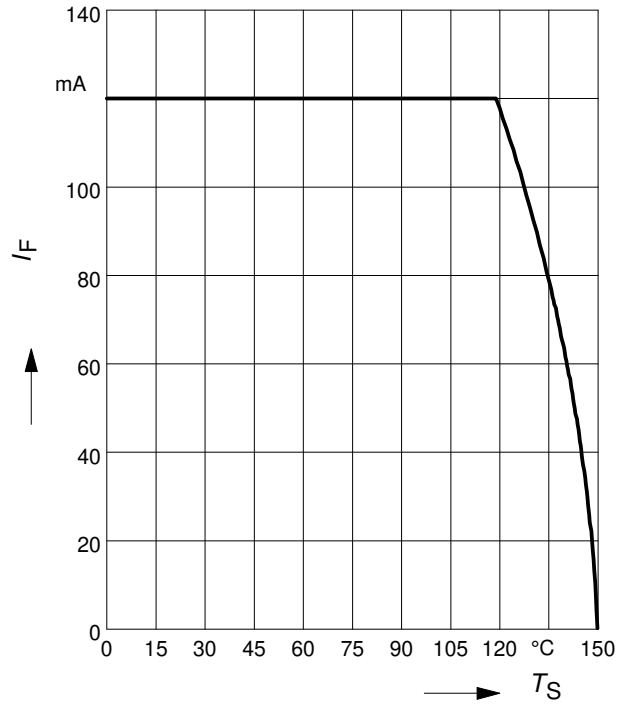
Forward current $I_F = f(T_S)$

BAS40-05W



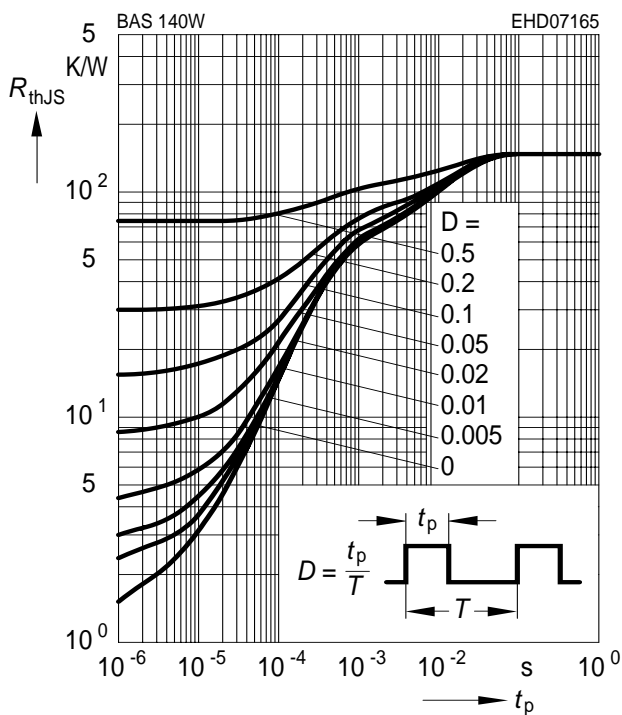
Forward current $I_F = f(T_S)$

BAS40-07W



Permissible Puls Load $R_{thJS} = f(t_p)$

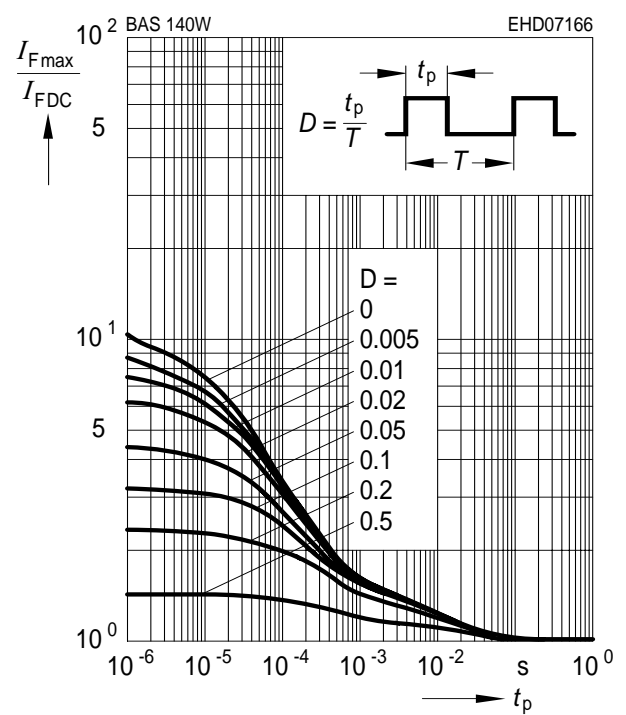
BAS140W



Permissible Pulse Load

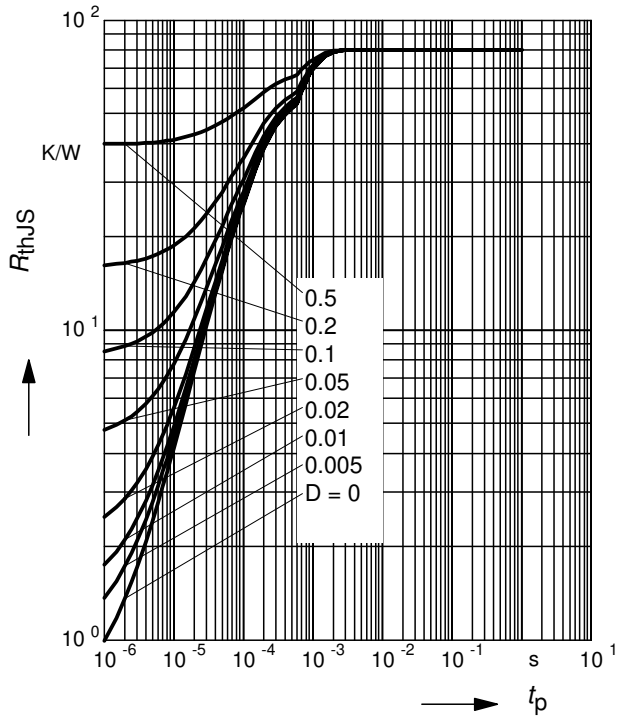
$I_{Fmax} / I_{FDC} = f(t_p)$

BAS140W



Permissible Puls Load $R_{thJS} = f(t_p)$

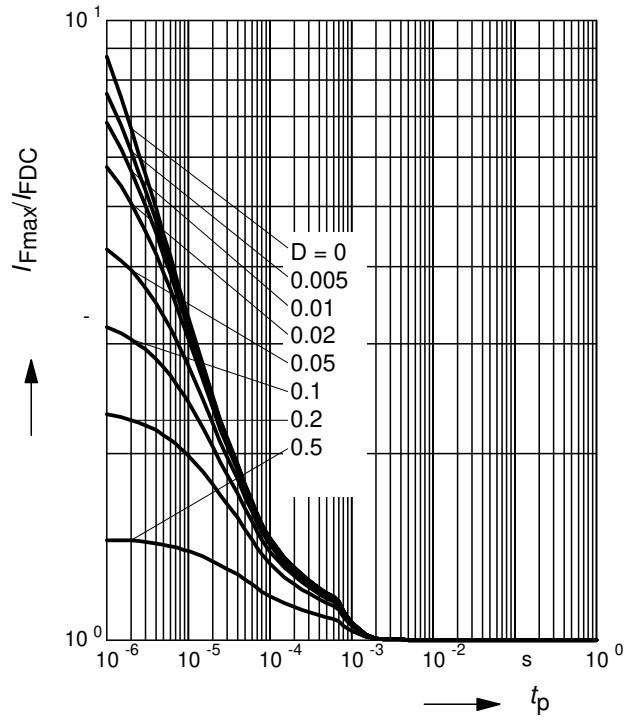
BAS40-02L



Permissible Pulse Load

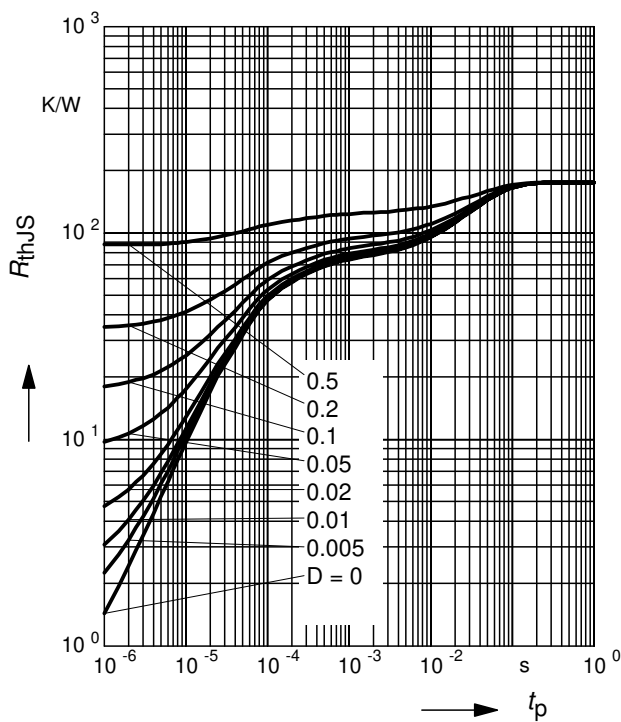
$I_{Fmax} / I_{FDC} = f(t_p)$

BAS40-02L



Permissible Puls Load $R_{thJS} = f(t_p)$

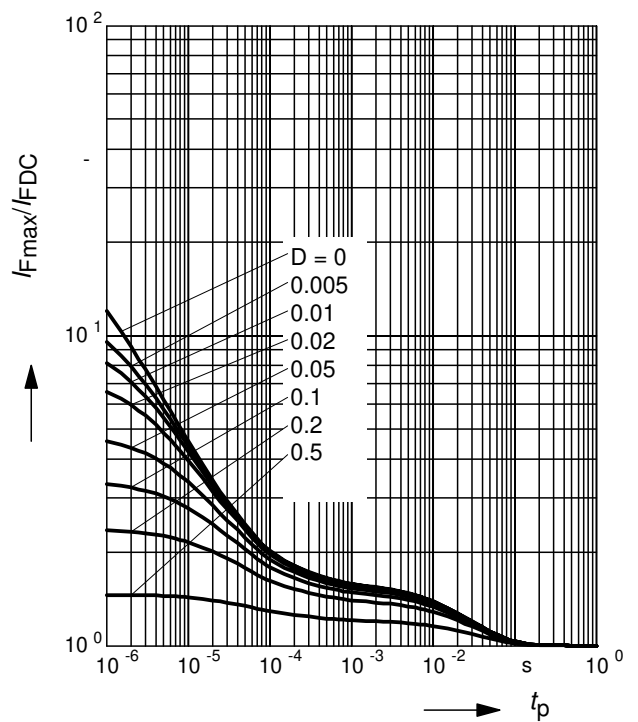
BAS40-06W



Permissible Pulse Load

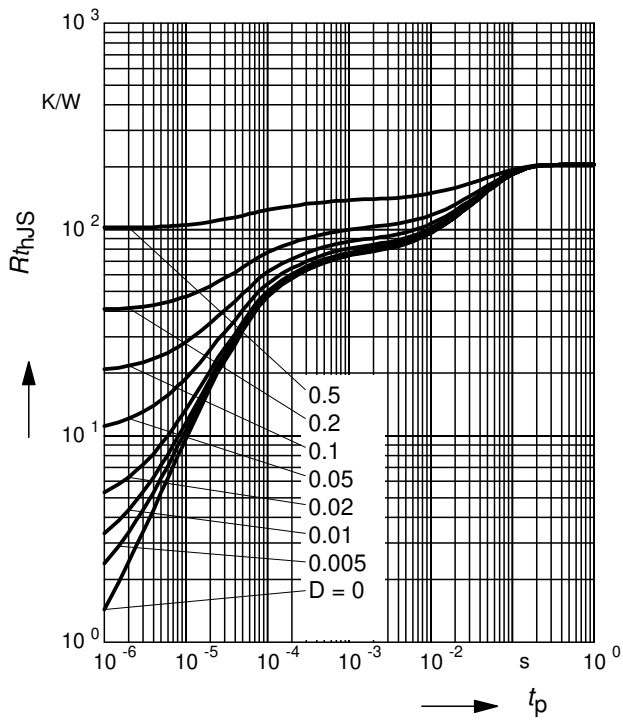
$I_{Fmax} / I_{FDC} = f(t_p)$

BAS40-06W



Permissible Puls Load $R_{thJS} = f(t_p)$

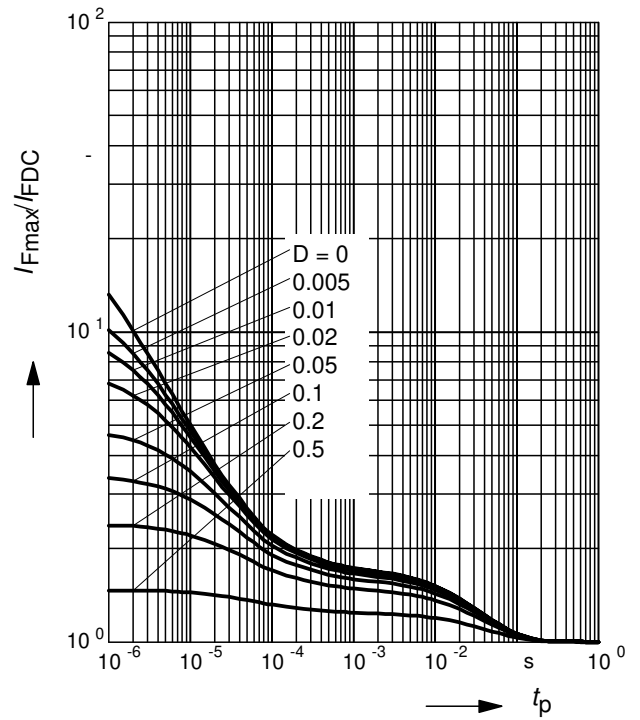
BAS40-05W



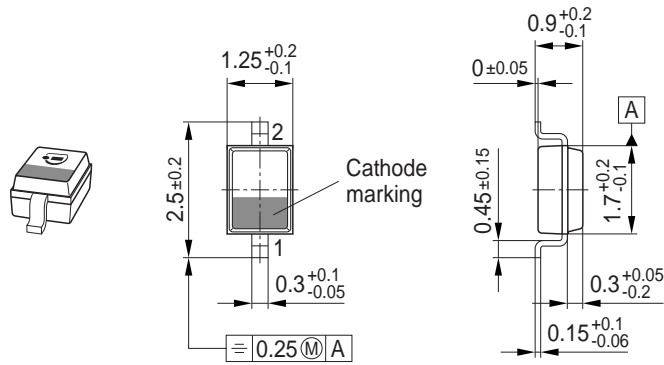
Permissible Pulse Load

$I_{Fmax}/I_{FDC} = f(t_p)$

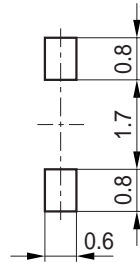
BAS40-05W



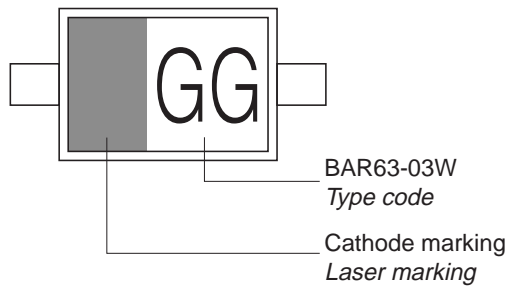
Package Outline



Foot Print

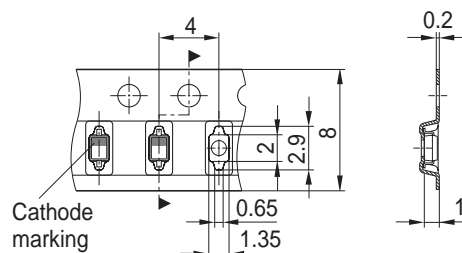


Marking Layout (Example)

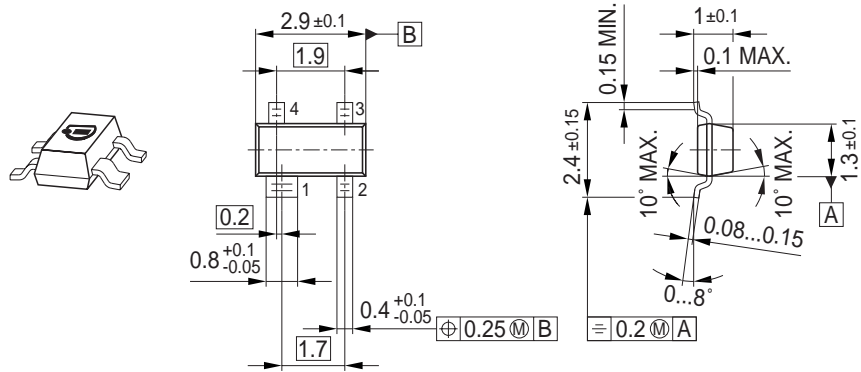


Standard Packing

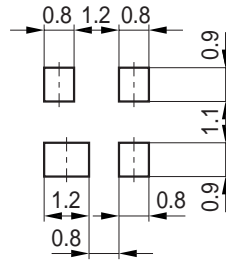
Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



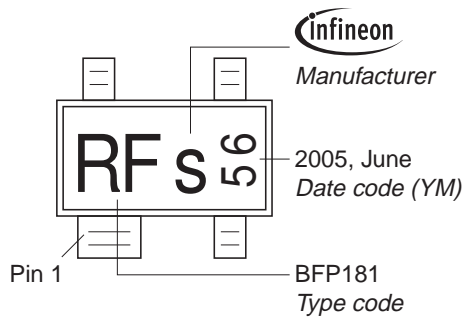
Package Outline



Foot Print

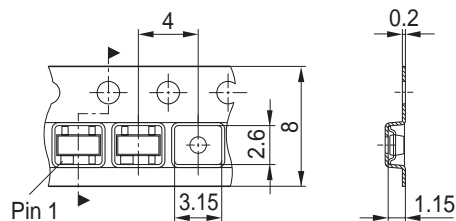


Marking Layout (Example)

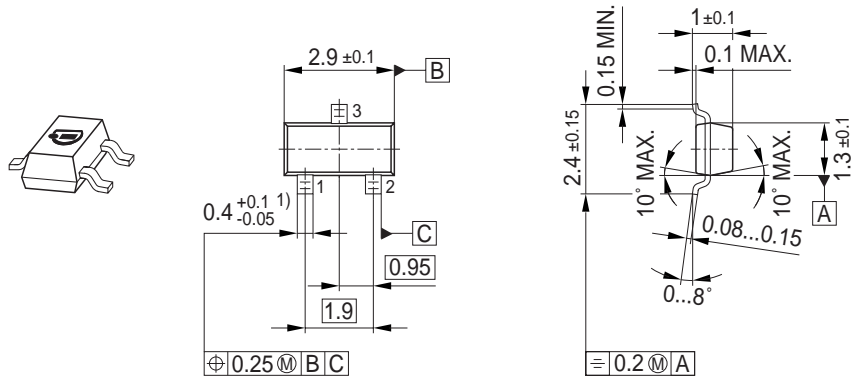


Standard Packing

Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel

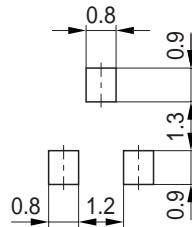


Package Outline

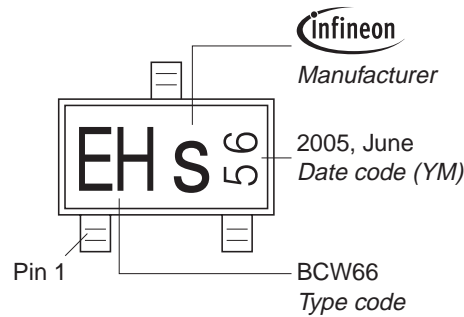


1) Lead width can be 0.6 max. in dambar area

Foot Print

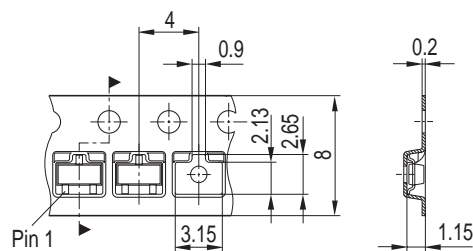


Marking Layout (Example)

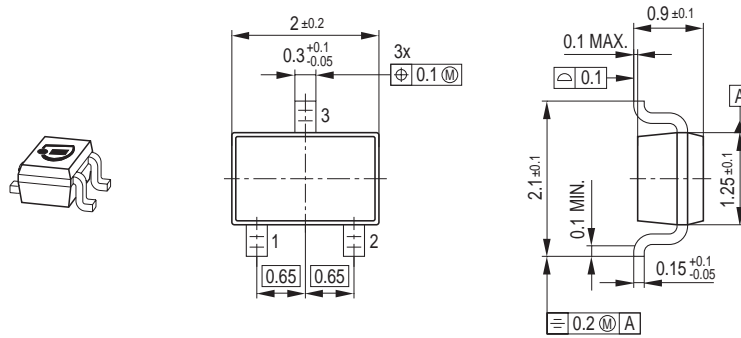


Standard Packing

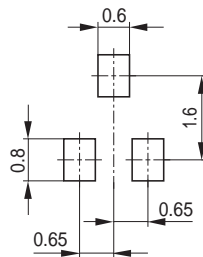
Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



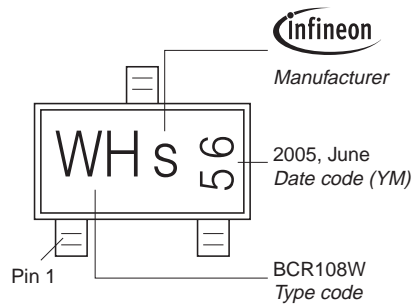
Package Outline



Foot Print

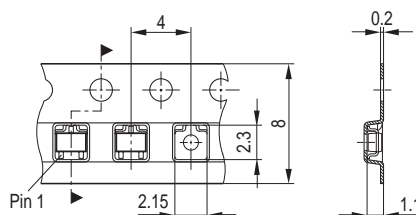


Marking Layout (Example)

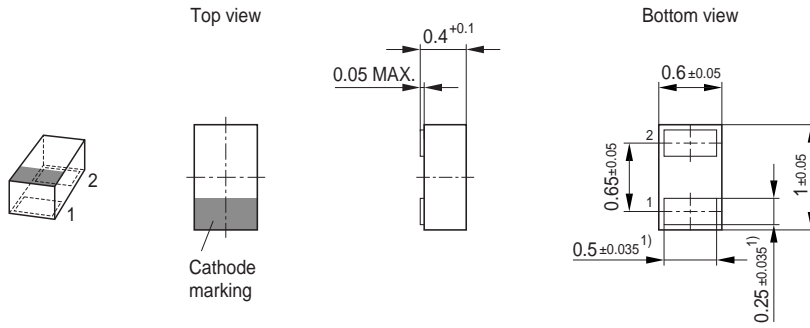


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel



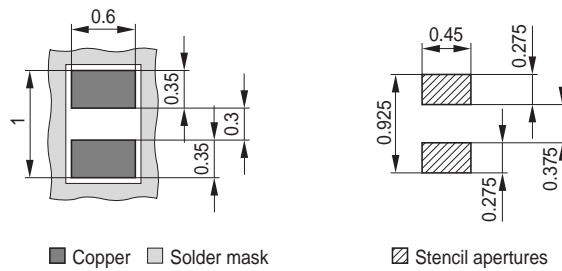
Package Outline



1) Dimension applies to plated terminal

Foot Print

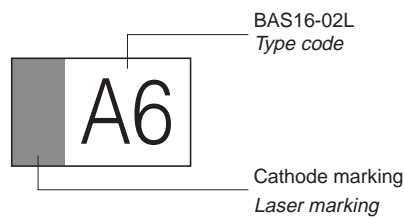
For board assembly information please refer to Infineon website "Packages"



■ Copper □ Solder mask

▨ Stencil apertures

Marking Layout (Example)

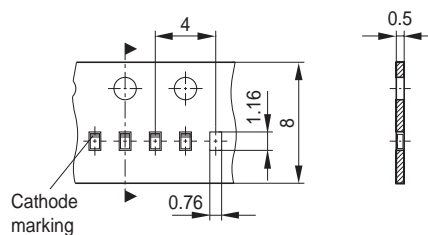


BAS16-02L
Type code

Cathode marking
Laser marking

Standard Packing

Reel \varnothing 180 mm = 15.000 Pieces/Reel
Reel \varnothing 330 mm = 50.000 Pieces/Reel (optional)



Edition 2006-02-01
Published by
Infineon Technologies AG
81726 München, Germany
© Infineon Technologies AG 2007.
All Rights Reserved.

Attention please!

The information given in this dokument shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie"). With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system.

Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.